

SSC8021GN1

P-Channel Enhancement Mode MOSFET with ESD Protection

> Features

| V _{DS} | V _{GS} | R _{DS(ON)} Typ. | Ι _D | ESD |
|-----------------|-----------------|--------------------------|----------------|-------|
| 201/ | 1401/ | 0.45Ω@-4V5 | 4.0 | 0.514 |
| -20V | ±12V | 0.6Ω@-2V5 | -1A | 0.5kV |

Description

This device particularly suits low voltage applications such as portable equipment, power management and other battery powered circuits, and low in-line power dissipation are needed in a very small outline surface mount package. The product does not contain Rohs substances such as lead and halogen.

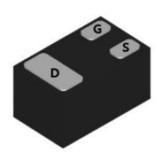
Applications

- Load Switch
- Portable Devices
- Signal Drive

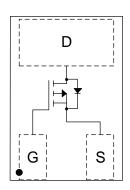
> Ordering Information

| Device | Package | Shipping |
|------------|------------|------------|
| SSC8021GN1 | DFN1006-3L | 10000/Reel |

Pin configuration



DFN1006-3L (Bottom View)



Pin Configuration (Top View)



Marking



Absolute Maximum Ratings (T_A=25[°]C unless otherwise noted)

| Symbol | Parameter | Ratings | Unit |
|------------------|---------------------------------------|---------|---------------|
| V _{DSS} | Drain-to-Source Voltage | -20 | V |
| V _{GSS} | Gate-to-Source Voltage | ±12 | V |
| I _D | Continuous Drain Current ^a | -1 | Α |
| I _{DM} | Pulsed Drain Current ^b | -3 | Α |
| P _D | Power Dissipation ^c | 0.45 | W |
| P _{DSM} | Power Dissipation ^a | 0.2 | W |
| TJ | Operation junction temperature | -55~150 | ${\mathbb C}$ |
| T _{STG} | Storage temperature range | -55~150 | ${\mathbb C}$ |

\succ Thermal Resistance Ratings (T_A=25°C unless otherwise noted)

| Symbol | Parameter | Maximum | Unit |
|------------------|---|---------|--------|
| R _{θJA} | Junction-to-Ambient Thermal Resistance ^a | 625 | · °C/W |
| Rejc | Junction-to-Case Thermal Resistance | 277 | C/VV |

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A=25 °C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

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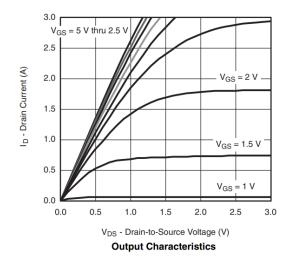


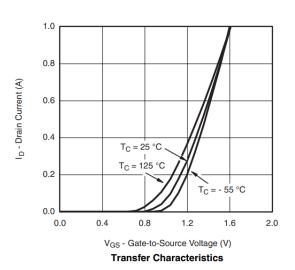
\succ Electrical Characteristics (T_A=25°C unless otherwise noted)

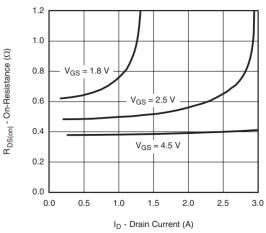
| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit |
|---------------------------------|----------------------|--|------|------|------|------|
| Drain-Source Breakdown Voltage | V _{(BR)DSS} | V _{GS} = 0V, I _D = -250μA | -20 | | | V |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = -250uA$ | -0.4 | -0.7 | -1 | V |
| | | V _{GS} = -4.5V, I _D = -0.5A | | 450 | 650 | |
| Drain-Source On-Resistance | R _{DS(on)} | V _{GS} = -2.5V, I _D = -0.3A | | 600 | 900 | mΩ |
| | | V _{GS} = -1.8V, I _D = -0.1A | | 800 | 1500 | |
| Zero Gate Voltage Drain Current | IDSS | V _{DS} = -16V, V _{GS} = 0V | | | -1 | μA |
| Gate-Source Leak Current | I _{GSS} | $V_{GS} = \pm 10V$, $V_{DS} = 0V$ | | | ±10 | μΑ |
| Transconductance | G _F s | V _{DS} = -5V, I _D = -0.5A | | 1 | | s |
| Forward Voltage | V _{SD} | V _{GS} = 0V, I _S = -0.15A | | | -1.3 | V |
| Input Capacitance | Ciss | \\ - 40\\\\ - 0\\ | | 25 | | |
| Output Capacitance | Coss | $V_{DS} = -10V, V_{GS} = 0V,$ | | 12 | | pF |
| Reverse Transfer Capacitance | Crss | f = 1MHz | | 5 | | |
| Turn-on Delay Time | T _{D(ON)} | | | 5 | | |
| Rise Time | Tr | $V_{GS} = -4.5V, V_{DS} = -10V,$ $R_{L} = 20\Omega, R_{G} = 3\Omega,$ | | 4 | | ne |
| Turn-off Delay Time | T _{D(OFF)} | NL - 2012, NG - 312, | | 12 | | ns |
| Fall Time | Tf | | | 7 | | |

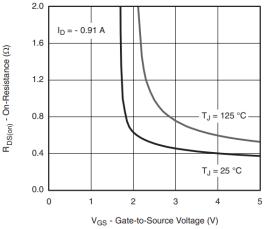


> Typical Performance Characteristics (T_A=25℃ unless otherwise noted)



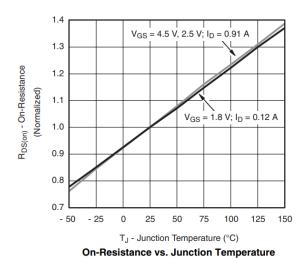


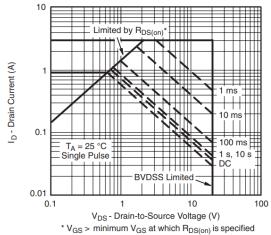






On-Resistance vs. Gate-to-Source Voltage

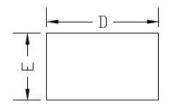




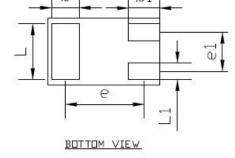
Safe Operating Area, Junction-to-Ambient

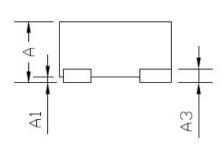


Package Information



TOP VIEW





SIDE VIEW

| PKG | DFN1006 | | |
|------|----------|----------------|------|
| REF. | MIN. | NDM. | MAX |
| Α | >0.4 | 6.77 | 0,50 |
| A1 | 0,00 | / - | 0.05 |
| A3 | 0.125REF | | |
| D | 0.95 | 1.00 | 1.05 |
| E | 0.55 | 0.60 | 0.65 |
| b | 0.20 | 0.25 | 0.30 |
| b1 | 0,20 | 0.30 | 0,40 |
| L | 0.45 | 0.50 | 0.55 |
| L1 | 0.10 | 0,15 | 0,20 |
| е | 0 | 0.675 | |
| e1 | 3 | 0,35 | |

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